

**ABSTRACT OF THE DISCLOSURE**

An electronic device includes a substrate, a lower  
conductive film formed on the substrate and a functional  
5 film formed on the lower conductive film. In the present  
invention, an adhesion of the lower conductive film on the  
side of the substrate is greater than or equal to 0.1 N/cm.  
The electronic device according to this invention exhibits  
high mechanical strength that makes it very reliable.  
10 This is because the invention prevents the physical  
exfoliation of the lower conductive film that is apt to  
occur during or after fabrication of the electronic device  
when the adhesion of the lower conductive film is lower  
than 0.1 N/cm.